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| **Day** | **Morning** | **Afternoon** |
| Mo | Introduction to PICs; waveguides and passive devices | Software installation; introduction to mode solver and propagator |
| Tue | Passive devices | Simulation of passive devices |
| Wed | Active devices (modulators & photodetectors) | Circuit simulation: theory and software description |
| Thu | Introduction to mask design: design rules and PDK overview | PIC fabrication & technology steps (photolithography, e-beam lithography, etching, depositions, metallizations, planarization) |
| Fri | PIC packaging techniques and design constraints | Project development presentation and discussion |
| Mo | Characterization and metrology, reliability (theory + lab tour) | Mask design with a tutor |
| Tue | INPHOTEC fabrication platforms | Mask design with a tutor |
| Wed | Mask design with a tutor / Clean Room live session | Clean Room live session / Mask design with a tutor |
| Thu | Packaging Lab session (beginners) | PIC Characterization Lab session |

**Course A PIC D&F**

**Course B PEIC Pack**

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| **Day** | **Morning** | **Afternoon** |
| Mo | Introduction to PEIC Packaging | Overview of players in photonic/electronic packaging |
| Tue | Technologies: Dicing, Polishing, Die attachment | Technologies: Wire bonding + Lab session 1 |
| Wed | Technologies: Flip chip | Lab session 2 |
| Thu | Technologies: Assembly, Alignment, Pigtailing | Lab session 3 |
| Fri | Photonic/electronic package design and layout | Flow chart and assembly methodology |